

PART INFORMATION	
Mfg Item Number	MPC8270CVRMIBA
Mfg Item Name	FPBGA 516 27*27*1.25P1.0
SUPPLIER	
Company Name	Freescale Semiconductor Inc
Company Unique ID	14-141-7928
Response Date	2018-03-20
Response Document ID	5201A1.45
Contact Name	Freescale Semiconductor Inc
Contact Title	Product Technical Support
Contact Phone	1-800-521-6274
Contact Email	support@freescale.com
Authorized Representative	Daniel Binyon
Representative Title	EPP Customer Response
Representative Phone	512-895-3406
Representative Email	eppanlst@freescale.com
URL for Additional Information	www.freescale.com
DECLARATION	
EU RoHS	Yes
Pb Free	Yes
HalogenFree	Yes
Plating Indicator	e2
EU RoHS Exemption(s)	
MANUFACTURING	
Mfg Item Number	MPC8270CVRMIBA
Mfg Item Name	FPBGA 516 27*27*1.25P1.0
Version	ALL
Weight	4.372550
UoM	g
Unit Volume	EACH
J-STD-020 MSL Rating	3
Peak Processing Temperature	245 C
Max Time at Peak Temperature	30 seconds
Number of Processing Cycles	3

RoHS	
RoHS Directive	2011/65/EU
RoHS Definition	RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) of homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material of Cadmium
RoHS Legal Definition	Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part(s) identified on this form contains lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a RoHS restricted substance) in excess of the applicable quantity limit identified below. If a homogeneous material within the part(s) contains a RoHS restricted substance in excess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Suppliers liability and the Companys remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Suppliers Standard Terms and Conditions of Sale applicable to such part(s) shall apply.
RoHS Declaration	1 - Item(s) do not contain RoHS restricted substances per the definition above
Supplier Acceptance	Accepted
Signature	Daniel Binyon
Exemption List Version	2012/51/EU
List of Freescale Accepted Exemptions	6(a) : Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0.35% lead by weight 6(b) : Lead as an alloying element in aluminium containing up to 0.4% lead by weight 6(c) : Copper alloy containing up to 4% lead by weight 7(a) : Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead) 7(b) : Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission, and network management for telecommunications 7(c)-I : Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound 7(c)-II : Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher 7(c)-III : Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC 7(c)-IV : Lead in PZT based dielectric ceramic materials for capacitors being part of integrated circuits or discrete semiconductors 15 : Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages

MATERIAL COMPOSITION

Homogeneous Material	Weight	SubstanceClass	Substance	CAS	Exemption	SubstanceWeight	UoM	SubPart PPM	SubPart%	ARTICLEPPM	ARTICLE%
Epoxy Die Attach	0.0267						g				
Epoxy Die Attach		Solvents, additives, and other materials	1,3,5-Triazine-2,4-diamine, 6-[2-(2-methyl-1H-imidazol-1-yl)ethyl]	38668-46-1		0.00022564	g	8451	0.8451	51	0.0051
Epoxy Die Attach		Plastics/polymers	Phenolic Polymer Resin, Epikote 155	9003-36-5		0.00345976	g	129579	12.9579	791	0.0791
Epoxy Die Attach		Plastics/polymers	4,4'-Dihydroxydiphenyl	92-88-6		0.00022564	g	8451	0.8451	51	0.0051
Epoxy Die Attach		Metals	Silver, metal	7440-22-4		0.02278896	g	853519	85.3519	5211	0.5211
Solder Balls - Pb Free, SnAg	0.426						g				
Solder Balls - Pb Free, SnAg		Metals	Silver, metal	7440-22-4		0.01491	g	35000	3.5	3409	0.3409
Solder Balls - Pb Free, SnAg		Metals	Tin, metal	7440-31-5		0.41109	g	965000	96.5	94016	9.4016
Die Encapsulant, Halogen-free	1.8181						g				
Die Encapsulant, Halogen-free		Plastics/polymers	Other Epoxy resins	-		0.109086	g	60000	6	24947	2.4947
Die Encapsulant, Halogen-free		Solvents, additives, and other materials	Carbon black	1333-86-4		0.018181	g	10000	1	4157	0.4157
Die Encapsulant, Halogen-free		Solvents, additives, and other materials	Other inorganic compounds.	-		0.026362	g	20000	2	8315	0.8315
Die Encapsulant, Halogen-free		Plastics/polymers	Other phenolic resins	-		0.009905	g	50000	5	20789	2.0789
Die Encapsulant, Halogen-free		Glass	Silica, vitreous	60676-86-0		1.563566	g	860000	86	357604	35.7604
Bonding Wire, Copper	0.025						g				
Bonding Wire, Copper		Metals	Copper, metal	7440-50-8		0.02425	g	970000	97	5545	0.5545
Bonding Wire, Copper		Solvents, additives, and other materials	Other miscellaneous substances (less than 5%).	-		0.00075	g	30000	3	171	0.0171
Organic Substrate	2.0417						g				
Organic Substrate		Solvents, additives, and other materials	Acrylonitrile/Butadiene copolymer, carboxyl terminated (26/74)	68891-46-3		0.00523696	g	2565	0.2565	1197	0.1197
Organic Substrate		Metals	Barium sulfate	7727-43-7		0.04860879	g	23808	2.3808	11116	1.1116
Organic Substrate		Metals	Copper, metal	7440-50-8		1.21698798	g	596066	59.6066	278324	27.8324
Organic Substrate		Plastics/polymers	2,2'-(1-methylethylidene)bis(4,1-phenyleneoxyethylene)bisoxazane	1675-54-3		0.005386	g	2638	0.2638	1231	0.1231
Organic Substrate		Metals	Gold, metal	7440-57-5		0.00365668	g	1791	0.1791	836	0.0836
Organic Substrate		Solvents, additives, and other materials	Other imidazole compounds	-		0.00044917	g	220	0.022	102	0.0102
Organic Substrate		Solvents, additives, and other materials	Other inorganic compounds.	-		0.00765442	g	3847	0.3847	1796	0.1796
Organic Substrate		Solvents, additives, and other materials	Silicon	7440-21-3		0.00062894	g	308	0.0308	143	0.0143
Organic Substrate		Nickel (external applications only)	Nickel	7440-02-0		0.01556592	g	7624	0.7624	3559	0.3559
Organic Substrate		Solvents, additives, and other materials	Other organic Silicon Compounds	-		0.00014904	g	73	0.0073	34	0.0034
Organic Substrate		Glass	Fibrous-glass-wool	65997-17-3		0.26726261	g	130902	13.0902	61122	6.1122
Organic Substrate		Plastics/polymers	Other acrylic resins	-		0.06160013	g	30171	3.0171	14067	1.4067
Organic Substrate		Plastics/polymers	Proprietary Material-Other Non-halogenated Epoxy resins	-		0.40831346	g	199987	19.9987	93381	9.3381
Silicon Semiconductor Die	0.03505						g				
Silicon Semiconductor Die		Solvents, additives, and other materials	Other miscellaneous substances (less than 5%).	-		0.000701	g	20000	2	160	0.016
Silicon Semiconductor Die		Glass	Silicon, doped	-		0.034349	g	980000	98	7855	0.7855

LINKS	
MCD LINK	
NXP website	http://www.nxp.com
GENERAL ENVIRONMENTAL COMPLIANCE LINKS	
RoHS signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-ROHS-DECLARATION.pdf
China RoHS	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/china-rohs:ENV_CHINA_ROHS_STRATEGY
REACH signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-REACH-STATEMENT.pdf
ELV signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-ELV-STATEMENT.pdf
Conflict Minerals statement	http://www.nxp.com/files/corporate/doc/support_info/NXP-STATEMENT-CONFLICT-MINERALS.pdf
NXP ENVIRONMENTAL INFORMATION	
Environmental Compliance website	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization:ABUENVPRFPRDX
FAQ	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/eco-product-faqs:ENVIRON_FAQ
Technical Service Request	http://www.nxp.com/support/sales-and-support:SUPPORTHOME
LINKS TO BLANK IPC1752 FORMS	
Blank IPC1752 v1.1 Form	http://www.NXP.com/files/abstract/corporate/ehs_epp/IPC-1752-2_v1.1_MCD_Template.pdf

IPC1752 XML LINKS

http://www.freescale.com/mcds/MPC8270CVRMIBA_IPC1752_v11.xml

http://www.freescale.com/mcds/MPC8270CVRMIBA_IPC1752A.xml